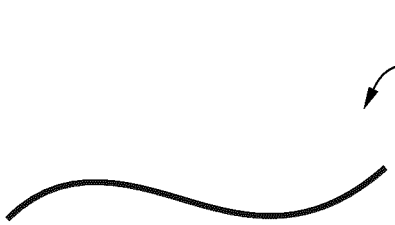

Fig. 1

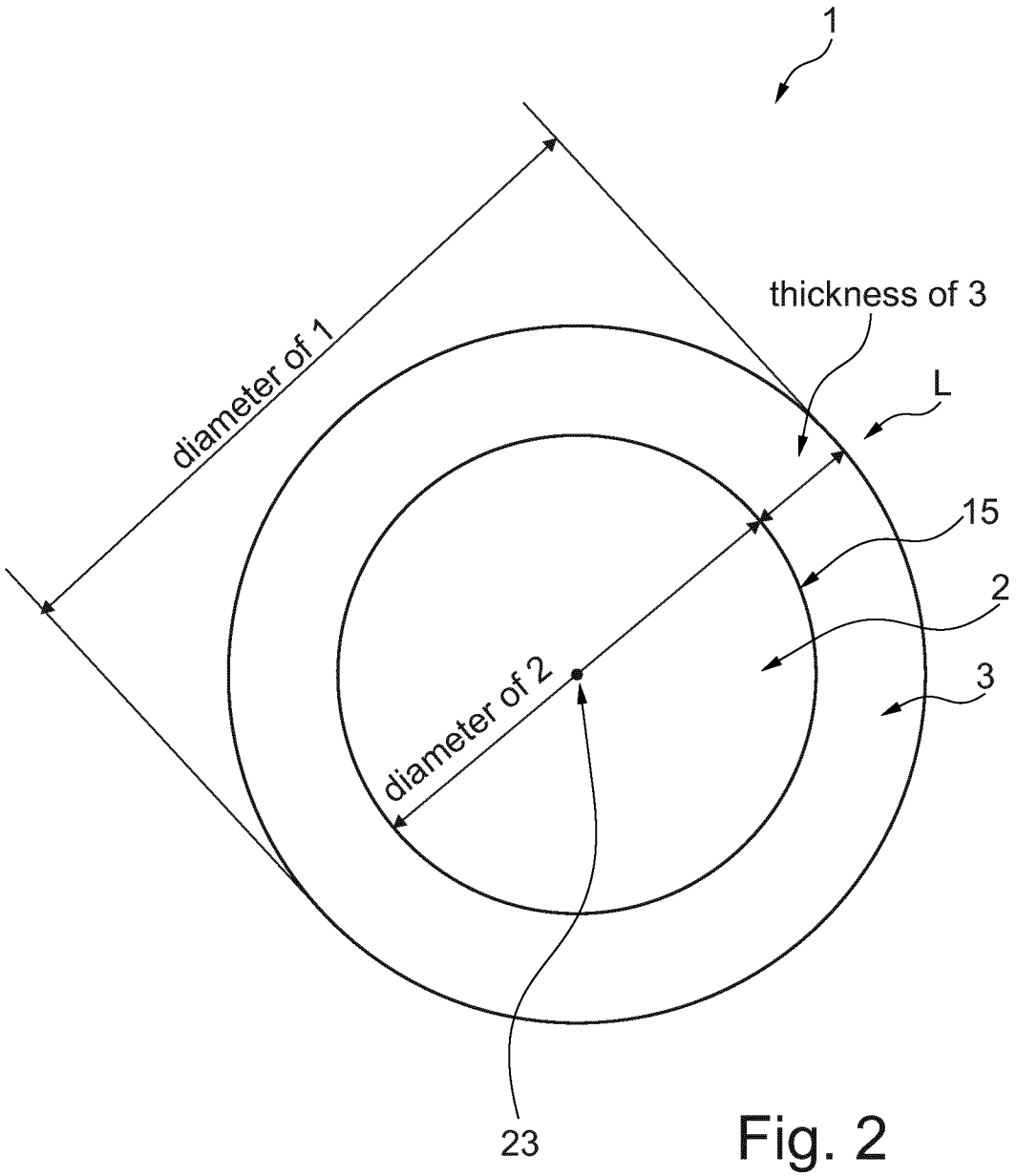

Fig. 2

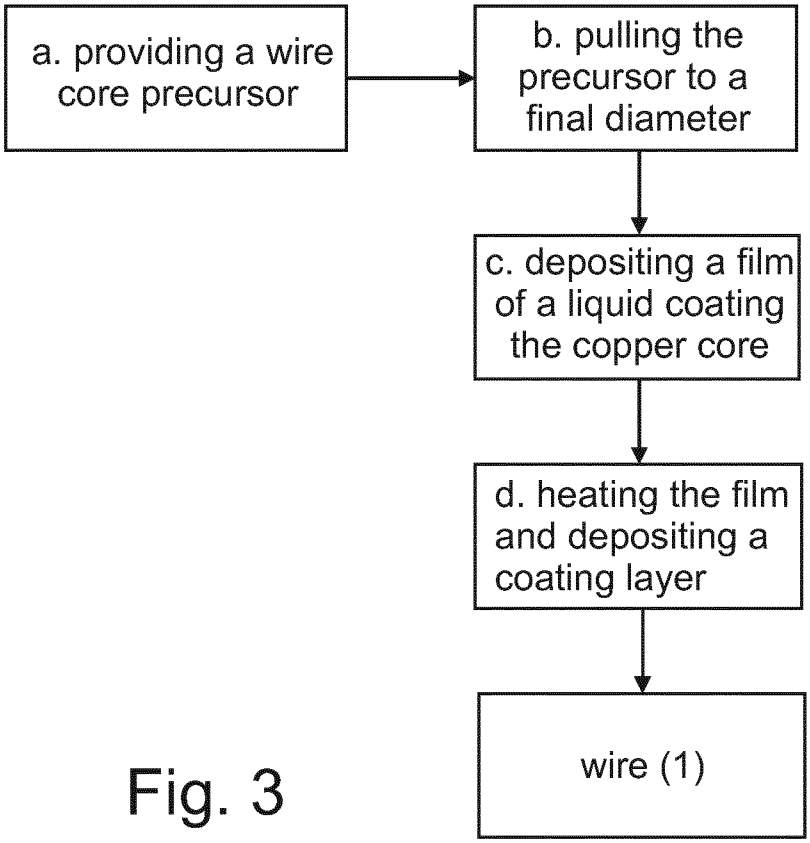
a. providing a wire core precursor
b. pulling the precursor to a final diameter
c. depositing a film of a liquid coating the copper core
d. heating the film and depositing a coating layer
wire (1)

Fig. 3

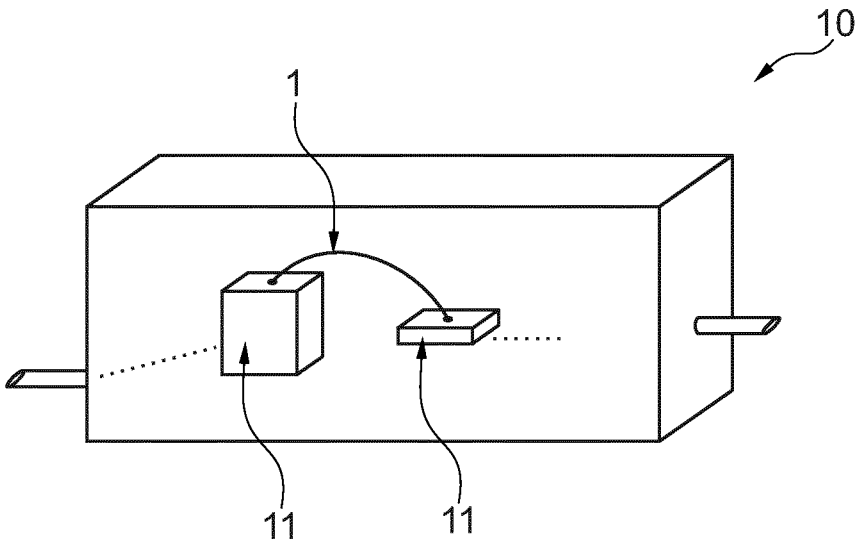
10
1
11
11

Fig. 4

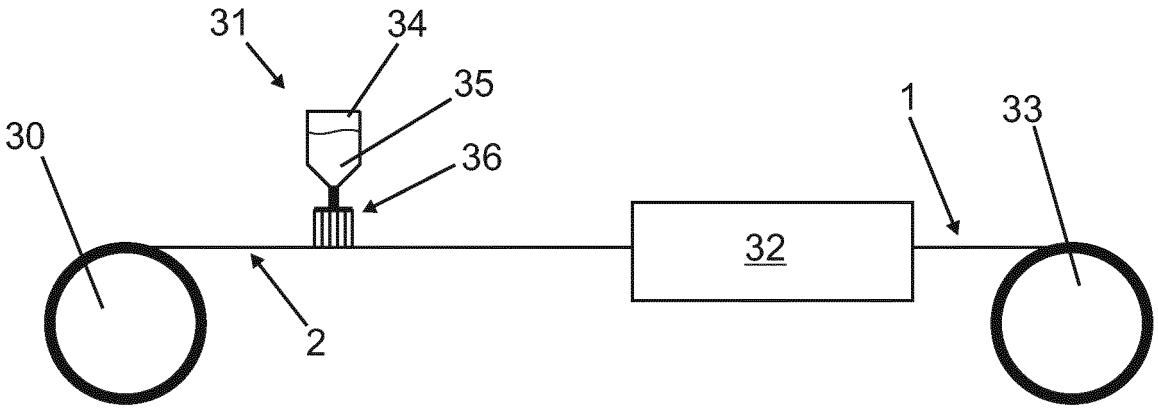
31
34
35
36
30
1
33
32
2

Fig. 5

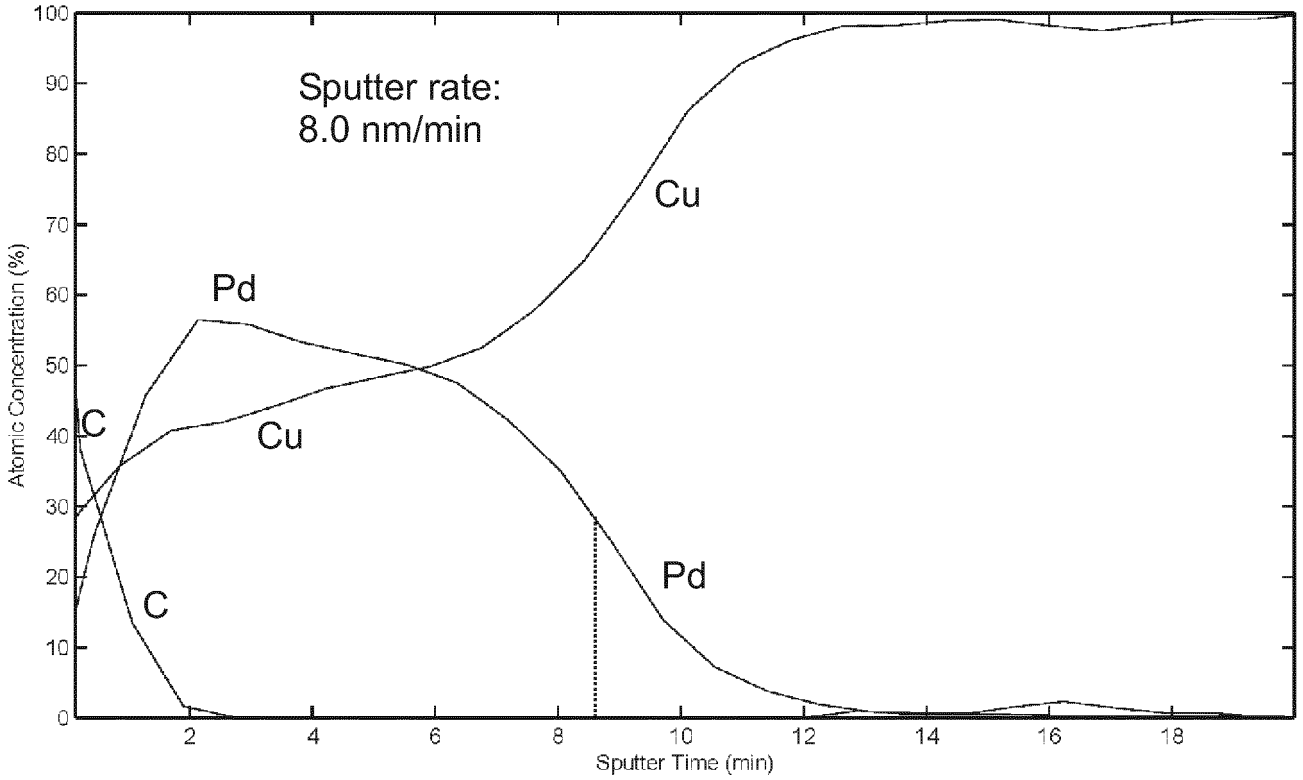
Sputter rate:
8.0 nm/min
Cu
Pd
C
Cu
Pd
C
Atomic Concentration (%)
Sputter Time (min)
0
10
20
30
40
50
60
70
80
90
100
2
4
6
8
10
12
14
16
18

Fig. 6